IN THE UNITED STATES PATENT & TRADEMARK OFFICE

Applicant:

Dingwei LU

U.S. Serial No.:

10/519,896

International Application No.: PCT/CN2003/00507

International Filing Date:

June 30, 2003

For: A MOULDING PROCESS OF COMPOSITE MATERIAL INCLUDING HIGH-

THERMAL CONDUCTOR AND ROOM-TEMPERATURE MAGNETIC REFRIGERANT

Date:

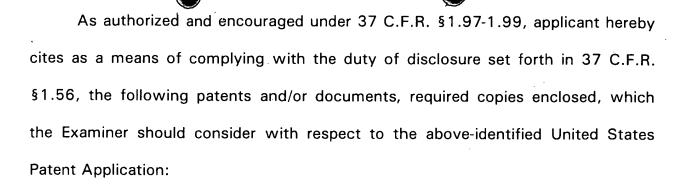
February 1, 2005

Mail Stop PCT Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

This invention relates to a molding process of composite material including high-thermal-conductor and room-temperature magnetic refrigerant comprises the steps of nesting magnetic refrigerant with high-thermal-conductor and connecting them mutually, especially making the room-temperature magnetic-thermal-conductor into sheet, strip or filament, inserting the high-thermal-conductors' sheet, strip or filament in the room-temperature magnetic refrigerant's sheet or filament and connecting them This invention has solved the application of the room-temperature magneticthermal-conductor, particularly the application of the room-temperature magneticthermal-conductor which is lower thermal-conductor, easier oxidation and powdering. The invention utilizes the high thermal-conductor to solve the problem of roomtemperature magnetic refrigerant which is poor in conventional heat exchange, meanwhile decreases the loss of the magnetic-thermal effect.



U.S. DOCUMENTS				
PATENT/DOCUMENT NO.	DATE	INVENTOR		
4,985,072	January 15, 1991	Sahashi et al.		
5,124,215	June 23, 1992	Hashimoto		
	FOREIGN DOCUMENTS			
PATENT/DOCUMENT NO.	DATE	COUNTRY		
1090313A	August 3, 1994	CN		

In accordance with 37 CFR 1.98(a)(2)(i) only the foreign and non-patent documents are required for the express purpose of providing the Patent and Trademark Office with an ample opportunity to evaluate the same and to arrive at an independent assessment of its materiality, if any, with regard to the examination of the application.

An examination of the present application considering the above documents is requested.

Respectfully submitted,

HUDAK, SHUNK & FARINE CO. LPA

Daniel J. Hudak //

Registration No. 25,879

DJH/lb 2020 Front Street Suite 307 Cuyahoga Falls, OH 44221-3257 (330) 535-2220

Sheet	1	of	
	-	-	

Form PTO-1449 U.S. Department of Commerce Atty. Docket No.: Serial No.: 10/519,896 Patent and Trademark Office CNIP-B-PCT-US LIST OF PRIOR ART CITED BY APPLICANT Applicant: Dingwei LU (Use several sheets if necessary) Filing Date: Group: **U.S. PATENT DOCUMENTS** Examiner **Document** Name Class Subclass Filing date if appropriate Initial Number AA4,985,072 January 15, 1991 Sahashi et al. ΑB 5,124,215 June 23, 1992 Hashimoto AC AD ΑE ΑF AG ΑH ΑI ΑJ ΑK **FOREIGN PATENT DOCUMENTS Document** Date Country Class Subclass **Translation** Number Yes No AL1090313A August 3, 1994 CN Х AM Х AN Х ΑO Х ΑP Х OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.) AR AŞ ΑT **EXAMINER DATE CONSIDERED**

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

#

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

Applicant:

Dingwei LU

U.S. Serial No.:

10/519,896

International Application No.: PCT/CN2003/00507

International Filing Date:

June 30, 2003

For: A MOULDING PROCESS OF COMPOSITE MATERIAL INCLUDING HIGH-

THERMAL CONDUCTOR AND ROOM-TEMPERATURE MAGNETIC REFRIGERANT

Date:

February 1, 2005

Mail Stop PCT Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

CERTIFICATE OF MAILING

Sir:

The undersigned hereby certifies that the attached INFORMATION DISCLOSURE STATEMENT, PTO FORM-1449s, AND ONE FOREIGN CITED REFERENCE were mailed to the Mail Stop PCT, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, with sufficient first-class postage, no special handling, on February 1, 2005, before 5:00 PM, thereby ensuring that such document(s) will be in the hands of the U.S. Postal Service by the close of business this day.

Respectfully submitted,

HUDAK, SHUNK & FARINE CO. LPA

By: Daniel J. Hudak

Registration No. 25,879

DJH/lb 2020 Front Street, Suite 307 Cuyahoga Falls, OH 44221 (330) 535-2220

Attorney Docket No.: CNIP-B-PCT-US

Enclosures: Return Postcard

Certificate of Mailing

Information Disclosure Statement, Form PTO-1449,

Copy of One Foreign Reference